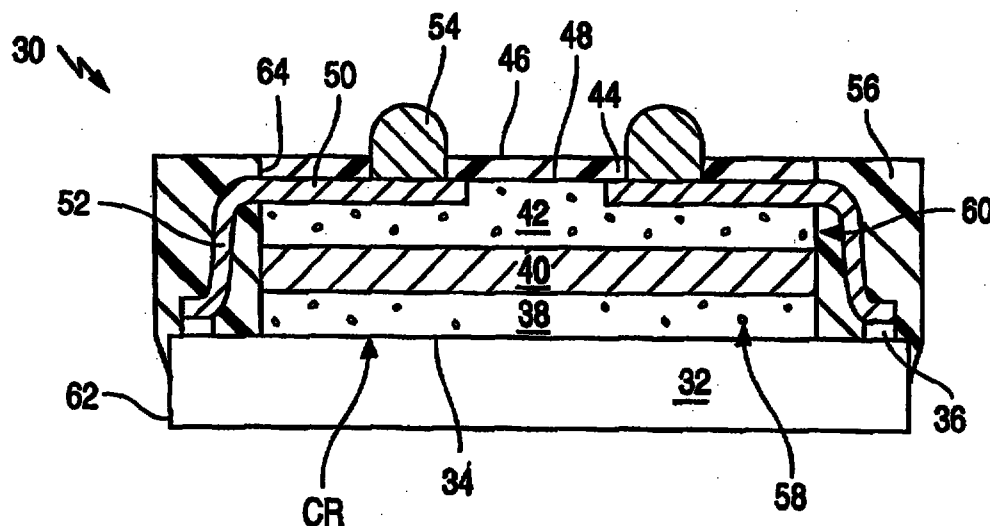




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(54) Title: METHOD AND CONSTRUCTION FOR THERMALLY ENHANCING A MICROELECTRONIC PACKAGE



(57) Abstract

A thermally enhanced package (30) for an integrated circuit, the integrated circuit (32) having a surface with bond pads (36) formed thereon, includes a heat sink structure (40) attached to a central region of the integrated circuit surface inward of the bond pads (36). The package further includes a substrate (44) attached to the heat sink structure. The heat sink structure includes a heat sink (40) and first, second adhesive layers (38, 42) between the heat sink (40) and the integrated circuit (32), substrate (44), respectively. The heat sink (40) enhances heat transfer between the integrated circuit (32) and the substrate (44). Further, the first, second adhesive layers (38, 42) decouple any difference in thermal expansion between the integrated circuit (32), the heat sink (40) and the substrate (44).